

-	0	((((vacuum or void or bubble or "air gap") SAME ((reduce or reduction or reducing) WITH (pressure or heating)) SAME resin) and semiconductor) NOT ("transfer mold" or "transfer molding")) and bump	USPAT; US-PGPUB	2002/05/07 18:13
-	5082	((vacuum or void or bubble or "air gap") WITH resin) SAME (pressure or heating)	USPAT; US-PGPUB	2002/05/09 10:17
-	1	("4,554,126").PN.	USPAT; US-PGPUB	2002/05/07 18:34
-	96466	(resin or encapsulant) SAME (pressure or heating)	USPAT; US-PGPUB	2002/05/09 10:46
-	159	((resin or encapsulant) SAME (pressure or heating)) and (wafer with bump)	USPAT; US-PGPUB	2002/05/09 10:19
-	98	((resin or encapsulant) SAME (pressure or heating)) and (wafer with bump)) and (void or air or bubble or pocket)	USPAT; US-PGPUB	2002/05/09 10:21
-	93	((resin or encapsulant) SAME (pressure or heating)) and (wafer with bump)) and (void or air or bubble or pocket)) and semiconductor	USPAT; US-PGPUB	2002/05/09 10:21
-	134642	(resin or encapsulant) SAME (pressure or heating or heat)	USPAT; US-PGPUB	2002/05/09 11:05
-	0	20010009342.URPN.	USPAT	2002/05/09 11:03
-	22489	"hot melt"	USPAT; US-PGPUB	2002/05/09 11:05
-	1082	"hot melt" and semiconductor	USPAT; US-PGPUB	2002/05/09 11:06
-	721	("hot melt" and semiconductor) and (resin or encapsulant or encapsulation)	USPAT; US-PGPUB	2002/05/09 11:06
-	7	((("hot melt" and semiconductor) and (resin or encapsulant or encapsulation)) and (wafer WITH bump)	USPAT; US-PGPUB	2002/05/09 11:07
-	27	(US-6352878-\$ or US-6350705-\$ or US-6350668-\$ or US-6281046-\$ or US-6278192-\$ or US-6235842-\$ or US-6181569-\$ or US-6103552-\$ or US-6063646-\$ or US-6344407-\$ or US-6365057-\$ or US-6307145-\$ or US-5965269-\$ or US-5804126-\$ or US-4554126-\$ or US-6225205-\$ or US-6114753-\$).did. or (US-20020027257-\$ or US-20010020737-\$ or US-20020001688-\$ or US-20020000658-\$ or US-20010042923-\$ or US-20020031868-\$ or US-20020030258-\$ or US-20020025667-\$ or US-20010009342-\$ or US-20010003058-\$).did.	USPAT; US-PGPUB	2002/05/09 13:51
-	3	((US-6352878-\$ or US-6350705-\$ or US-6350668-\$ or US-6281046-\$ or US-6278192-\$ or US-6235842-\$ or US-6181569-\$ or US-6103552-\$ or US-6063646-\$ or US-6344407-\$ or US-6365057-\$ or US-6307145-\$ or US-5965269-\$ or US-5804126-\$ or US-4554126-\$ or US-6225205-\$ or US-6114753-\$).did. or (US-20020027257-\$ or US-20010020737-\$ or US-20020001688-\$ or US-20020000658-\$ or US-20010042923-\$ or US-20020031868-\$ or US-20020030258-\$ or US-20020025667-\$ or US-20010009342-\$ or US-20010003058-\$).did.) and (void with pressure)	USPAT; US-PGPUB	2002/05/09 13:55
-	11	(void with pressure) and (semiconductor) and (wafer with bump)	USPAT; US-PGPUB	2002/05/09 13:58
-	36	((void or bubble) SAME pressure) and (semiconductor) and (wafer with bump)	USPAT; US-PGPUB	2002/05/09 14:18
-	49	(void SAME vacuum) and (semiconductor) and (wafer with bump)	USPAT; US-PGPUB	2002/05/09 14:14

-	46	((void SAME vacuum) and (semiconductor) and (wafer with bump)) NOT (((void or bubble) SAME pressure) and (semiconductor) and (wafer with bump))	USPAT; US-PGPUB	2002/05/09 14:21
-	34585	resin WITH pressure	USPAT; US-PGPUB	2002/05/09 14:23
-	1136	(resin WITH pressure) and wafer	USPAT; US-PGPUB	2002/05/09 14:21
-	751	((resin WITH pressure) and wafer) and semiconductor	USPAT; US-PGPUB	2002/05/09 14:22
-	0	"L751" and (encapsulant or encapsulating or filler or protective)	USPAT; US-PGPUB	2002/05/09 14:22
-	374	((resin WITH pressure) and wafer) and semiconductor) and (encapsulant or encapsulating or filler or protective)	USPAT; US-PGPUB	2002/05/09 14:22
-	62	((resin WITH pressure) and wafer) and semiconductor) and (encapsulant or encapsulating or filler or protective)) and void	USPAT; US-PGPUB	2002/05/09 16:08
-	1	("4,900,485").PN.	USPAT; US-PGPUB	2002/05/09 14:27
-	3	((("6126532") or ("6225205") or ("5300735"))).PN.	USPAT; US-PGPUB	2002/05/09 16:17
-	2	((("6126428") or ("6214649"))).PN.	USPAT; US-PGPUB	2002/05/09 16:41
-	1	("6214649").PN.	USPAT; US-PGPUB	2002/05/09 17:18
-	1	("5926694").PN.	USPAT; US-PGPUB	2002/05/09 17:19
-	6119	(resin or epoxy or encapsulant) SAME (void or "air pocket" or hole) SAME pressure	USPAT; US-PGPUB	2002/05/09 17:49
-	1920	((resin or epoxy or encapsulant) SAME (void or "air pocket" or hole) SAME pressure) and (atmosphere or atmospheric or subatmospheric)	USPAT; US-PGPUB	2002/05/09 17:50
-	53	((resin or epoxy or encapsulant) SAME (void or "air pocket" or hole) SAME pressure) and (atmosphere or atmospheric or subatmospheric)) and (wafer and packaging)	USPAT; US-PGPUB	2002/05/09 17:50